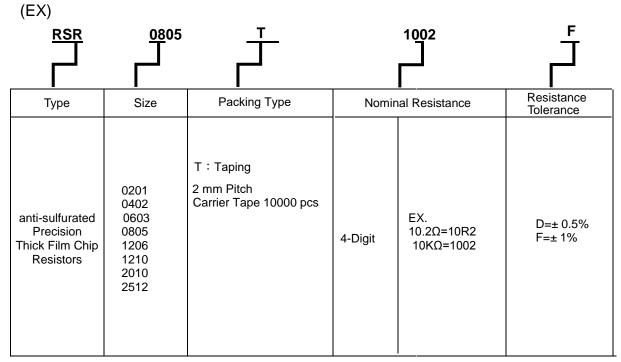


Document No.IE-SP-145Released Date2019/05/15Page No.1

1 Scope:

- 1.1 This specification is applicable to lead-free and halogen-free RSR series anti-sulfurated precision thick film chip resistors.
- 1.2 Superior Sulfur resistant capability (Refer to ASTM-B-809-95&EIA977sulfurvapor test).
- 1.3 The product is for general purpose.

2 Explanation Of Part Number:



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Document No.IE-SP-145Released Date2019/05/15

Page No.

2

3 General Specifications:

	Rated				Resistance Range
Туре	Power at 70℃	Max. Working Voltage	Max. Overload Voltage	T.C.R (ppm / ℃)	D(±0.5%) \ F(±1%) E-24 \ E-96
RSR (0201)	1 20 W	30V	60V	±100	$100\Omega\!\leq\!R\!<\!1M\Omega$
RSR (0402)	1 16 W	50V	100V	±50	$100\Omega\!\leq\!R\!<\!1M\Omega$
RSR (0603)	1 10 W	75V	150V	±50	$100\Omega\!\leq\!R\!<\!1M\Omega$
RSR (0805)	- <u>1</u> 8 W	150V	300V	±50	$10\Omega{\leq}R{<}1M\Omega$
RSR (1206)	$\frac{1}{4}$ W	200V	400V	±50	$10\Omega{\leq}R{<}1M\Omega$
RSR (1210)	1 2 W	200V	400V	±50	$10\Omega{\leq}R{<}1M\Omega$
RSR (2010)	$\frac{3}{4}$ W	200V	400V	±50	$100\Omega\!\leq\!R\!<\!1M\Omega$
RSR (2512)	1W	200V	400V	±50	$10\Omega{\leq}R{<}1M\Omega$
0	perating Tem	perature Ran	ge	-5	5°C ~+155°C(0201:−55°C ~ +125°C)

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Document No.IE-SP-145Released Date2019/05/15Page No.3

3.1 Power Derating Curve:

Туре	RSR (0201)	Other
Operating Temperature Range	− 55 °C ~ + 125 °C	− 55 °C ~ + 155 °C
	centigrade to 125 degrees centigrade, the power	If the ambient temperature exceeds 70 degrees centigrade to 155 degrees centigrade, the power can be modified by the curve as below.
Figure	00 00 00 00 00 00 00 00 00 00	⁷⁰ ⁸⁰ ⁶⁰ ⁴⁰ ²⁰ ₋₅₅ ²⁰ ⁴⁰ ⁶⁰ ⁴⁰ ²⁰ ²⁰ ²⁰ ⁴⁰ ⁶⁰ ⁴⁰ ²⁰ ²⁰ ²⁰ ⁴⁰ ⁶⁰ ⁴⁰ ⁴⁰ ²⁰ ²⁰ ²⁰ ⁴⁰ ⁶⁰ ⁴⁰ ⁴⁰ ²⁰ ²⁰ ²⁰ ⁴⁰ ⁶⁰ ⁴⁰ ⁴⁰ ²⁰ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁵⁵ ²⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴⁰ ⁴

3.2 Voltage Rating or Current Rating:

Rated Voltage: DC voltage or AC voltage (rms) based on the rated power. The voltage can be calculated by the following formula. If the calculated value exceeds the Max. voltage specified in the Table 3, the Max. voltage rating is set as the voltage rating.

$$E = \sqrt{R \times P} \quad \stackrel{\text{E= Voltage rating (V)}}{\underset{\text{R= Nominal resistance(\Omega)}}{\overset{\text{V}}{\underset{\text{R= Nominal resistance}}{\overset{\text{V}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{R= Nominal resistance}}{\overset{\text{N}}{\underset{\text{N}}}{\underset{N}}{\overset{N}}{\underset{N}}{\overset{N}}{\underset{N}}{\overset{N}}{\underset{N}}{\underset{N}}{\overset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N}}{\underset{N$$

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Document No.IE-SP-145Released Date2019/05/15

Page No.

4

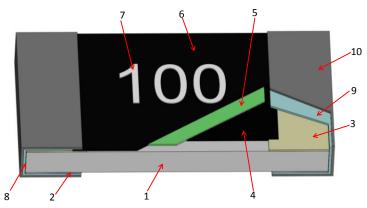
Unit:mm

4 Dimensions:

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, L	

	Dimension	L	W	н	L1	L2
Туре	Size Code					
RSR	0201	0.60±0.03	0.30±0.03	0.23±0.03	0.10±0.05	0.15±0.05
RSR	0402	1.00±0.10	0.50±0.05	0.30±0.05	0.20±0.10	0.25±0.10
RSR	0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.15	0.30±0.15
RSR	0805	2.00±0.10	1.25±0.10	0.50±0.10	0.35±0.20	0.35±0.20
RSR	1206	3.05±0.10	1.55±0.10	0.50±0.10	0.45±0.20	0.35±0.20
RSR	1210	3.05±0.10	2.55±0.10	0.55±0.10	0.50±0.20	0.50±0.20
RSR	2010	5.00±0.20	2.50±0.20	0.55±0.10	0.60±0.20	0.60±0.20
RSR	2512	6.30±0.20	3.20±0.20	0.55±0.10	0.60±0.20	0.60±0.20

5 Structure Graph:



1	Ceramic substrate	6	2nd Protective coating
2	Bottom inner electrode	7	Marking
3	Top inner electrode	8	Terminal inner electrode
4	Resistive layer	9	Ni plating
5	1st Protective coating	10	Sn plating

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Page No.

5

6 Reliability Test:

6.1 Electrical Performance Test

Item	Conditions	Specifications
nem	Conditions	Resistors
Temperature Coefficient of Resistance	TCR (ppm/°C) = $\frac{(R2-R1)}{R1(T2-T1)}$ x10 ⁶ R1: Resistance at room temperature R2: Resistance at -55°C or +125°C T1: Room temperature T2: Temperature -55°C or +125°C	Refer to item 3. general specifications
	Refer to JIS-C5201-1 4.8	
Short Time Overload	Applied 2.5 times rated voltage for 5 seconds and release the load for about 30 minutes, then measure its resistance variance rate. (Rated voltage refer to item 3. general specifications)	∆R%=±1.0%
	Refer to JIS-C5201-1 4.13	
Insulation Resistance	Put the resistor in the fixture, add 100 VDC in + ,- terminal for 60 sec then measured the insulation resistance between electrodes and insulating enclosure or between electrodes and base material. Refer to JIS-C5201-1 4.6 Metal block measuring Point A Metal block measuring Point B Base material Specimen Pressurizing by spring	
Dielectric Withstand	Put the resistor in the fixture, add VAC (see spec. below) in +,- terminal for. RSR0805, 1206,1210,2010,2512 apply 500 VAC 1 minute. RSR0201, 0402,0603 apply 300 VAC 1 minute.	No short or burned on the appearance.
	Refer to JIS-C5201-1 4.7	

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Page No.

6

6.2 Mechanical Performance Test

Conditions The resistor mounted on the board applied 5N proce on the sample rear for 10 sec. (RSR020 the resistor mounted on the board slowly ad ample rear until the sample termination is b <u>0 JIS-C5201-1 4.16</u> ted resistor be immersed into isopropyl alco 6 minutes, then the resistor is left in the roor asured its resistance variance rate. <u>0 JIS-C5201-1 4.29</u> ditioning: tested resistor in the apparatus of PCT, at a C, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resistance is ature for 2 hours or more. ethod: istor be immersed into solder pot in temperal c, then the resistor is left as placed under me ad its solder area. <u>0 JIS-C5201-1 4.17</u> method 1 (solder pot test): ted resistor be immersed into molten solder econds. Then the resistor is left in the room	21:3N) dd force on the preakdown. ohol of 20~25 m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5°C	Other≧5N RSR01 : △R%=±1.0% Other : △R%=±0.5% Solder coverage over 95%
broce on the sample rear for 10 sec. (RSR020) the resistor mounted on the board slowly ad ample rear until the sample termination is b <u>0 JIS-C5201-1 4.16</u> ted resistor be immersed into isopropyl alco is minutes, then the resistor is left in the roor asured its resistance variance rate. <u>0 JIS-C5201-1 4.29</u> ditioning: tested resistor in the apparatus of PCT, at a C, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resistance rate ethod: istor be immersed into solder pot in temperation c, then the resistor is left as placed under me ad its solder area. <u>0 JIS-C5201-1 4.17</u> method 1 (solder pot test): ted resistor be immersed into molten solder	21:3N) dd force on the preakdown. ohol of 20~25 m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5°C	mechanical damage. Test 2: RSR0201≧ 3N Other≧5N RSR01 : ΔR%=±1.0% Other : ΔR%=±0.5% Solder coverage over 95%
The resistor mounted on the board slowly ad ample rear until the sample termination is b <u>0 JIS-C5201-1 4.16</u> ted resistor be immersed into isopropyl alco is minutes, then the resistor is left in the roor asured its resistance variance rate. <u>0 JIS-C5201-1 4.29</u> ditioning: tested resistor in the apparatus of PCT, at a c, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resist ature for 2 hours or more. ethod: istor be immersed into solder pot in temperation c, then the resistor is left as placed under me et its solder area. <u>0 JIS-C5201-1 4.17</u> method 1 (solder pot test): ted resistor be immersed into molten solder	d force on the preakdown. ohol of 20~25 m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5°C	Test 2: RSR0201≧ 3N Other≧5N RSR01 : ∆R%=±1.0% Other : ∆R%=±0.5% Solder coverage over 95%
ample rear until the sample termination is b <u>o JIS-C5201-1</u> 4.16 ted resistor be immersed into isopropyl alco is minutes, then the resistor is left in the roor asured its resistance variance rate. <u>o JIS-C5201-1</u> 4.29 ditioning: tested resistor in the apparatus of PCT, at a c, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resistance ature for 2 hours or more. ethod: istor be immersed into solder pot in temperation c, then the resistor is left as placed under mean ed its solder area. <u>o JIS-C5201-1</u> 4.17 method 1 (solder pot test): ted resistor be immersed into molten solder	oreakdown. ohol of 20~25 m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5°C	Other≧5N RSR01 : △R%=±1.0% Other : △R%=±0.5% Solder coverage over 95%
b JIS-C5201-1 4.16 ted resistor be immersed into isopropyl alco minutes, then the resistor is left in the roor asured its resistance variance rate. b JIS-C5201-1 4.29 ditioning: tested resistor in the apparatus of PCT, at a c, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resistature for 2 hours or more. ethod: istor be immersed into solder pot in temperation c, then the resistor is left as placed under me ad its solder area. b JIS-C5201-1 4.17 method 1 (solder pot test): ted resistor be immersed into molten solder	ohol of 20~25 m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5°C	RSR01 : ∆R%=±1.0% Other : ∆R%=±0.5% Solder coverage over 95%
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5 minutes, then the resistor is left in the roor asured its resistance variance rate. 5 JIS-C5201-1 4.29 ditioning: tested resistor in the apparatus of PCT, at a C, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resistature for 2 hours or more. ethod: istor be immersed into solder pot in temperators c, then the resistor is left as placed under medits solder area. 5 JIS-C5201-1 4.17 method 1 (solder pot test): ted resistor be immersed into molten solder	m for 48 hrs., a temperature .22×10 ⁵ Pa for istor in room ature 235±5℃	Other : ∆R%=±0.5% Solder coverage over 95%
asured its resistance variance rate. <u>JIS-C5201-1</u> 4.29 ditioning: tested resistor in the apparatus of PCT, at a c, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested residence ature for 2 hours or more. ethod: istor be immersed into solder pot in temperators c, then the resistor is left as placed under mean ed its solder area. <u>JIS-C5201-1</u> 4.17 method 1 (solder pot test): ted resistor be immersed into molten solder	a temperature .22×10 ⁵ Pa for istor in room ature 235±5℃	Solder coverage over 95%
b JIS-C5201-1 4.29 ditioning: tested resistor in the apparatus of PCT, at a C, humidity of 100% RH, and pressure of 1. on of 4 hours. Then after left the tested resi ature for 2 hours or more. ethod: istor be immersed into solder pot in tempera c, then the resistor is left as placed under m ed its solder area. b JIS-C5201-1 4.17 method 1 (solder pot test): ted resistor be immersed into molten solder	.22×10 ⁵ Pa for istor in room ature 235±5°∁	
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method 1 (solder pot test): ted resistor be immersed into molten solder		
method 1 (solder pot test): ted resistor be immersed into molten solder		
ted resistor be immersed into molten solder		Test item 1:
	r of260+5/-0℃	
	-	△R%=±1.0%
		(2).No evidence of electrode
method 2 (solder pot test):		damage.
ted resistor be immersed into molten solder	r of260+5/-0℃	No side conductive peeling
econds. Then the resistor is left as placed u	-	off.
cope to observe its solder area.		Test item 2:
		(1).Solder coverage over 95%
method 3 (Electric iron test):		(2).The underlying material
ting temperature : 350±10°C		(such as ceramic) shall no
		be visible at the crest corn
	on, as after	area of the electrode. Test item 3:
	1.14	(1).Variance rate on resistance
		$\Delta R\% = \pm 1.0\%$
		(2).No evidence of electrode
JIS-C5201-1 4.18		damage.
		No side conductive peeling
		off.
	iron preheating time : 3+1/-0 sec ting the electric iron on electrode termination	iron preheating time : 3+1/-0 sec ting the electric iron on electrode termination, as after p placed the iron over 60 min. and measured its nee variance rate.



Document No.IE-SP-145Released Date2019/05/15Page No.7

Item	Conditions	Specifications Resistors
Joint Strength of Solder	Bending Strength: Solder tested resistor on to PC board. Add force in the middle down, and under load measured its resistance variance rate. D:RSR0402, 0603,0805=5mm RSR0201,1206,1210=3mm RSR2010,2512=2mm	 (1).Variance rate on resistance △R%=±1.0% (2).No evidence of mechanical damage. No terminal peeling off and core body cracked.

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6.3 Environmental Test

Item	Conditions			Specifications
nem				Resistors
Resistance to Dry Heat	Put tested resistor in chamber under temperature 155±5°C for 1000 +48/-0 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate.			∆R%=±1.0%
Thermal Shock	Put the tested resistor in the chamber used which shown in the following table shall consecutively. Then leaving the teste temperature for 1 hours, and measure its in the testing Condition Lowest Temperature	II be repeated 30 d resistor in the resistance variance	0 times e room	∆R%=±0.5%
Shock	Highest Temperature	-55±5℃ 125±5℃ 15 minutes each		
Loading Life in Moisture	Refer to MIL-STD 202 Method 107 Put the tested resistor in the chamber un relative humidity 90~95% and load the ra- on, 30 minutes off, total 1000 hours. Then in room temperature for 60 minutes, an variance rate.	ted voltage for 90 leaving the tested	minutes resistor	∆R%=±2.0%
Load Life	Refer to JIS-C5201-1 4.24 Put the tested resistor in chamber under load the rated voltage for 90 minutes on, hours. Then leaving the tested resistor in minutes, and measure its resistance varia Refer to JIS-C5201-1 4.25	30 minutes off, to room temperatur	tal 1000	∆R%=±2.0%
Sulfuration Test	Put the tested resistor in sulfur vapor, at a temperature of $105\pm2^{\circ}$ C for 750hrs Refer to ASTM-B-809-95&EIA977			∆R=±4.0%

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7 Plating Thickness:

- 7.1 Ni:≥2µm
- 7.2 Sn(Tin):≥3µm
- 7.3 Sn(Tin):Mate Sn

8 Measurement Point:

Measure from bottom electrodes			Unit : mm
A	DIM TYPE	Α	В
	RSR0201	0.44±0.05	0.22±0.05
	RSR0402	0.80±0.05	0.24±0.05
	RSR0603	1.35±0.05	0.35±0.05
	RSR0805	1.80±0.05	0.35±0.05
	RSR1206	2.90±0.05	0.35±0.05
 Current Terminal 	RSR1210	2.90±0.05	0.35±0.05
 Voltage Terminal 	RSR2010	4.50±0.05	1.15±0.05
	RSR2512	5.90±0.05	1.60±0.05

9 Rule of package empty quantity:

9.1 Empty quantity for each reels not allowed to exceed 0.1% of the whole quantity, and continuous 2pcs (included) empty are also unallowed.

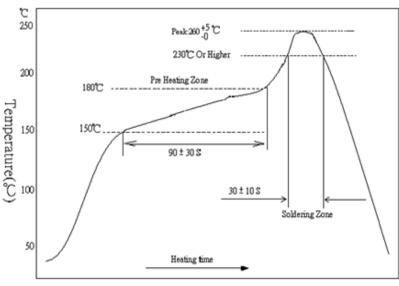
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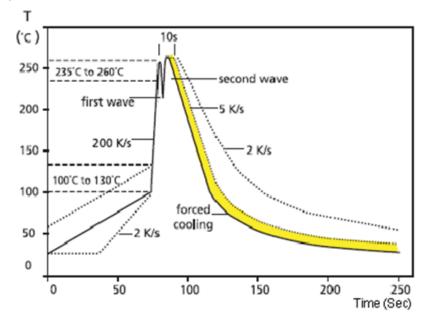
10 Technical application notes (This is for recommendation, please customer perform adjustment according to actual application):

10.1 Recommend Soldering Method:

10.1.1 Lead Free IR Reflow Soldering Profile



Remark: The peak temperature of soldering heat is 260 +5/-0 °C for 10 seconds.
10.1.2Lead Free Double-Wave Soldering Profile. (This applies to 0603 and above size products)



10.1.3Soldering Iron: temperature $350^{\circ}C \pm 10^{\circ}C$, dwell time shall be less than 3 sec.

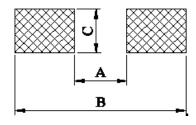
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Document No.IE-SP-145Released Date2019/05/15Page No.11

10.2 Recommend Land Pattern Design (For Reflow Soldering):

When a component is soldered, the resistance after soldering changes slightly depending on the size of the soldering area and the amount of soldering. When designing a circuit, it is necessary to consider the effect of a decrease or increase in its resistance.



			Unit.mm
DIM	А	В	С
RSR0201	0.3	1.0	0.4
RSR0402	0.5	1.5	0.6
RSR0603	0.8	2.1	0.9
RSR0805	1.2	3.0	1.3
RSR1206	2.2	4.2	1.6
RSR1210	2.2	4.2	2.8
RSR2010	3.5	6.1	2.8
RSR2512	3.8	8.0	3.5

Unit:mm

10.3 Environment Precautions:

This specification product is for general electronic use, RALEC will not be responsible for any damage, cost or loss caused by using this specification product in any special environment. If other applications need to confirm with RALEC.

If consumer intends to use our Company product in special environment or condition (including but not limited to those mentioned below), then will need to make individual recognition of product features and reliability accordingly.

- (a) Used in high temperature and humidity environment;
- (b) Exposed to sea breeze or other corrosive gas, such as $CI_2 \cdot H_2S \cdot NH_3 \cdot SO_2$ and NO_2 ;
- (c) Used in non-verified liquids including water, oil, chemical and organic solvents;
- (d) Using non-verified resin or other coating material to seal or coat our Company product;
- (e) After soldering, it is necessary to use water-soluble detergents to clean residual solder fluxes, even though no-clean fluxes are recommended;

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10.4 Momentary Overload Precautions:

The product might be out of function when momentary overloaded. Please make sure to avoid momentary overloading while using and preserving.

- 10.5 Operation and Processing Precautions:
 - (a) Avoid damage to the edge of resistor and protective layer caused by mechanical stress.
 - (b) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
 - (c) Make sure the power rating is under the limit when using the resistor. When power rating is over the limit, the resister will be overloaded. There might be machinery damage due to the climbing temperature.
 - (d) If the resister will be exposed under massive impact load (shock wave) in a short period of time, the working environment must be set up well before use.
 - (e) Please make evaluation and confirmation when the product is well used in your company and have a through consideration of it's fail-safe design to ensure the system safety.

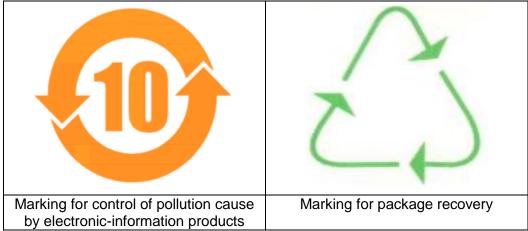
11 Stock period:

- 11.1 The temperature condition must be controlled as $25\pm5^{\circ}$, and the R.H. must be Controlled at 60±15%. The stock can maintain quality level in two years.
- 11.2 Please avoid the mentioned harsh environment below when storing to ensure product Performance and its' weldability. Places exposed to sea breeze or other corrosive gas, such as Cl2 Vec H2S Vec NH3 Vec SO2 and NO2.
- 11.3 When the product is moved and stored, please ensure the correct orientation of the box. Do not drop or squeeze the box. Otherwise, the electrode or the body of the product may be damaged.

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12 The carton packaged for electronic-information products is made by the symbol as follows: (For china)



13 Attachments:

13.1 Document Revise Record (QA-QR-027)

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